# 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION

SLLS349J - JUNE 1999 - REVISED MARCH 2004

- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V<sub>CC</sub> Supply
- Operates Up To 250 kbit/s
- Five Drivers and Three Receivers
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Always-Active Noninverting Receiver Output (ROUT1B)
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
  - SNx5C3238
- Applications
  - Battery-Powered Systems, PDAs, Notebooks, Subnotebooks, Laptops, Palmtop PCs, Hand-Held Equipment, Modems, and Printers

#### **DB OR PW PACKAGE** (TOP VIEW) 28 T C1+ C2+[ GND 2 27 N+ 26 V<sub>CC</sub> C2-[]3 V−∏4 25 C1-DOUT1 5 24 | DIN1 DOUT2 6 23 | DIN2 DOUT3 7 22 DIN3 21 🛮 ROUT1 RIN1 ¶8 20 **∏** ROUT2 RIN2 9 DOUT4 10 19 DIN4 RIN3 [] 11 18 ROUT3 17 DIN5 DOUT5 12 FORCEON 16 | ROUT1B 15 NVALID FORCEOFF 14

# description/ordering information

The MAX3238 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/us driver output slew rate.

# **ORDERING INFORMATION**

TA	PACKAGE	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	CCOD (DD)	Tube of 50	MAX3238CDB	MAY2020C
000 to 7000	SSOP (DB)	Reel of 2000	MAX3238CDBR	MAX3238C  MA3238C  MAX3238I
−0°C to 70°C	TOCOR (DIA)	Tube of 50	MAX3238CPW	MA20200
	TSSOP (PW)	Reel of 2000	MAX3238CPWR	MA3238C
	0000 (DD)	Tube of 50	MAX3238IDB	MAYOOO
4000 / 0500	SSOP (DB)	Reel of 2000	MAX3238IDBR	MAX32381
-40°C to 85°C	TSSOP (PW)	Tube of 50	MAX3238IPW	MB3238I
	1330F (FW)	Reel of 2000	MAX3238IPWR	IVIDOZOOI

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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# description/ordering information (continued)

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μA. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V, or has been between –0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 µs. Refer to Figure 5 for receiver input levels.

#### **Function Tables**

#### **EACH DRIVER**

		INI	PUTS	OUTPUT	
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	DOUT	DRIVER STATUS
Х	Χ	L	X	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown plus disabled
L	L	Н	<30 s	Н	Normal operation with
Н	L	Н	<30 s	L	auto-powerdown plus enabled
L	L	Н	>30 s	Z	Powered off by
Н	L	Н	>30 s	Z	auto-powerdown plus feature

H = high level, L = low level, X = irrelevant, Z = high impedance

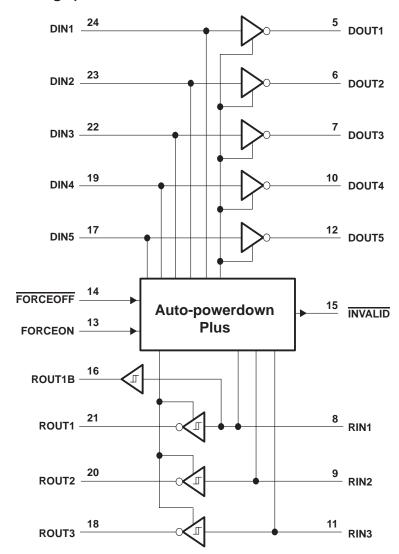
### **EACH RECEIVER**

		INP	UTS	OUTP	UTS	
RIN1	RIN2-RIN3	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	RECEIVER STATUS
L	Χ	L	X	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT1B is active
L	L	Н	<30 s	L	Н	
L	Н	Н	<30 s	L	L	Normal operation with
Н	L	Н	<30 s	Н	Н	auto-powerdown plus
Н	Н	Н	<30 s	Н	L	disabled/enabled
Open	Open	Н	>30 s	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



# logic diagram (positive logic)



# **MAX3238**

# 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION SLLS349J – JUNE 1999 – REVISED MARCH 2004

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	0.3 V to 7 V
Negative output supply voltage range, V- (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V <sub>I</sub> : Driver (FORCEOFF, FORCEON)	0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V <sub>O</sub> : Driver	
Receiver (INVALID)	0.3 V to V <sub>CC</sub> + 0.3 V
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): DB package	
PW package	62°C/W
Operating virtual junction temperature, T <sub>J</sub>	150°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
  - 2. Maximum power dissipation is a function of T<sub>J</sub>(max), θ<sub>JA</sub>, and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

# recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Owner have been		V <sub>CC</sub> = 3.3 V	3	3.3	3.6	
	Supply voltage		V <sub>CC</sub> = 5 V	4.5	5	5.5	٧
.,	Driver and control high level in a valuable as	DIN FORCES FORCES	V <sub>CC</sub> = 3.3 V	2			V
VIH	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V <sub>CC</sub> = 5 V	2.4			
$V_{IL}$	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				8.0	V
٧ <sub>I</sub>	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ <sub>I</sub>	Receiver input voltage			-25		25	V
Τ.	T <sub>A</sub> Operating free-air temperature		MAX3238C	0		70	00
١A			MAX3238I	-40		85	°C

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAME	TER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
Ц	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V <sub>CC</sub>		0.5	2	mA
Icc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
	$(T_A = 25^{\circ}C)$	Auto-powerdown plus enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

<sup>‡</sup> All typical values are at  $V_{CC}$  = 3.3 V or  $V_{CC}$  = 5 V, and  $T_A$  = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047  $\mu$ F and C2-C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



#### **DRIVER SECTION**

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TES	TEST CONDITIONS			TYP <sup>†</sup>	MAX	UNIT
Vон	High-level output voltage	All DOUT at R <sub>L</sub> = $3 \text{ k}\Omega$ to	GND		5	5.4		V
VOL	Low-level output voltage	All DOUT at $R_L = 3 \text{ k}\Omega$ to	GND		-5	-5.4		V
lн	High-level input current	VI = VCC				±0.01	±1	μΑ
Ι <sub>Ι</sub> L	Low-level input current	V <sub>I</sub> at GND				±0.01	±1	μΑ
	0	V <sub>CC</sub> = 3.6 V,	VO = 0 V			±35	±60	A
los	Short-circuit output current‡	V <sub>CC</sub> = 5.5 V,	VO = 0 V			±40	±100	mA
r <sub>O</sub>	Output resistance	$V_{CC}$ , V+, and V- = 0 V,	V <sub>O</sub> = ±2 V		300	10M		Ω
	Outrat la also as assument	FORCEOFF = GND	$V_0 = \pm 12 \text{ V},$	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25	^
loff	Output leakage current	FORCEOFF = GND	$V_0 = \pm 10 \text{ V},$	V <sub>CC</sub> = 4.5 V to 5.5 V			±25	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CO	TEST CONDITIONS			MAX	UNIT
	Maximum data rate	C <sub>L</sub> = 1000 pF, One DOUT switching,	$R_L = 3 \text{ k}\Omega$ , See Figure 1	150	250		kbit/s
t <sub>sk(p)</sub>	Pulse skew§	C <sub>L</sub> = 150 pF to 2500 pF	R <sub>L</sub> = 3 kΩ to 7 kΩ, See Figure 2		100		ns
CD(4*)	Slew rate, transition region	V <sub>CC</sub> = 3.3 V,	C <sub>L</sub> = 150 pF to 1000 pF	6		30	1///
SR(tr)	(see Figure 1)	$V_{CC}$ = 3.3 V, $R_L$ = 3 kΩ to 7 kΩ	$C_{I} = 150 \text{ pF to } 2500 \text{ pF}$	4		30	V/μs

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .



<sup>\$</sup> Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at  $V_{CC}$  = 3.3  $V \pm 0.15$  V; C1–C4 = 0.22  $\mu$ F at  $V_{CC}$  = 3.3  $V \pm 0.3$  V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

<sup>§</sup> Pulse skew is defined as |tplh - tphl| of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

#### RECEIVER SECTION

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
Vон	High-level output voltage	I <sub>OH</sub> = -1 mA	VCC-0.6 V	V <sub>CC</sub> -0.1 V		V	
VOL	Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V	
.,	Decitive as less less of the school decities	V <sub>CC</sub> = 3.3 V		1.5	2.4		
V <sub>IT+</sub>	Positive-going input threshold voltage	V <sub>CC</sub> = 5 V		1.8	2.4	V	
.,	N	V <sub>CC</sub> = 3.3 V	0.6	1.2		.,	
V <sub>IT</sub> _	Negative-going input threshold voltage	V <sub>CC</sub> = 5 V	0.8	1.5		V	
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.3		V	
l <sub>off</sub>	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μΑ	
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN TYPT	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	0 450 5 0 5 5 5 5 5	150		ns
tPHL	Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See Figure 3	150		ns
t <sub>en</sub>	Output enable time	0 450 5 B 010 0 5 5 5 5 5 5	200		ns
tdis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200		ns
tsk(p)	Pulse skew <sup>‡</sup>	See Figure 3	50		ns

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

NOTE 4: Testing supply conditions are C1–C4 = 0.1  $\mu$ F at  $V_{CC}$  = 3.3  $V \pm 0.15$  V; C1–C4 = 0.22  $\mu$ F at  $V_{CC}$  = 3.3  $V \pm 0.3$  V; and C1 = 0.047  $\mu$ F and C2-C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.



<sup>‡</sup>Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

#### **AUTO-POWERDOWN PLUS SECTION**

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP† N	ΛΑΧ	UNIT
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>			2.7	V
V <sub>T</sub> -(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V <sub>CC</sub>	-0.3		0.3	V
VOH	INVALID high-level output voltage	I <sub>OH</sub> = -1 mA, FORCEON = GND, FORCEOFF = V <sub>CC</sub>	V <sub>CC</sub> -0.6			V
V <sub>OL</sub>	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$ , FORCEON = GND, FORCEOFF = $V_{CC}$			0.4	V

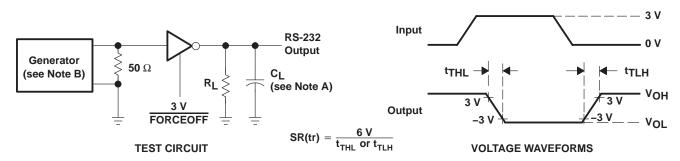
<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP <sup>†</sup>	MAX	UNIT
<sup>t</sup> valid	Propagation delay time, low- to high-level output		0.1		μs
<sup>t</sup> invalid	Propagation delay time, high- to low-level output		50		μs
ten	Supply enable time		25		μs
t <sub>dis</sub>	Receiver or driver edge to auto-powerdown plus	15	30	60	S

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$  or  $V_{CC} = 5 \text{ V}$ , and  $T_A = 25^{\circ}\text{C}$ .

#### PARAMETER MEASUREMENT INFORMATION

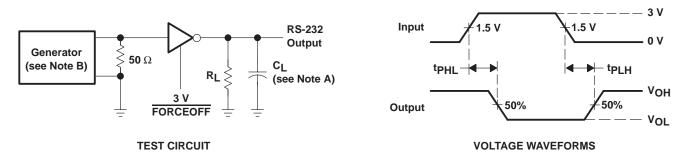


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns.  $t_f \le 10$  ns.

Figure 1. Driver Slew Rate

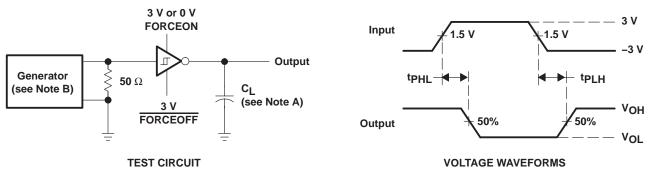
#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \le 10$  ns,  $t_f \le 10$  ns.

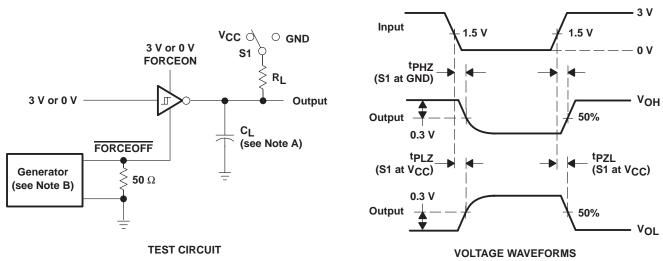
Figure 2. Driver Pulse Skew



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_\Gamma \le 10$  ns,  $t_f \le 10$  ns.

Figure 3. Receiver Propagation Delay Times



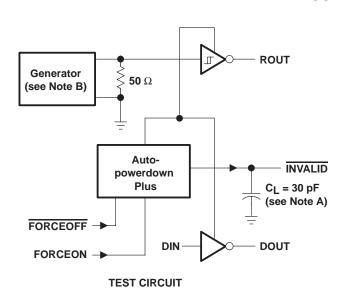
NOTES: A.  $C_L$  includes probe and jig capacitance.

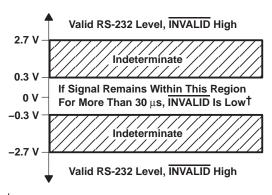
- B. The pulse generator has the following characteristics:  $Z_Q = 50 \Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.
- C. tpLz and tpHz are the same as tdis.
- D. tpzL and tpzH are the same as ten.

Figure 4. Receiver Enable and Disable Times



#### PARAMETER MEASUREMENT INFORMATION





† Auto-powerdown plus disables drivers and reduces supply current to 1  $\mu$ A.

- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. The pulse generator has the following characteristics: PRR = 5 kbit/s,  $Z_{O}$  = 50  $\Omega$ , 50% duty cycle,  $t_f \le 10$  ns,  $t_f \le 10$  ns.

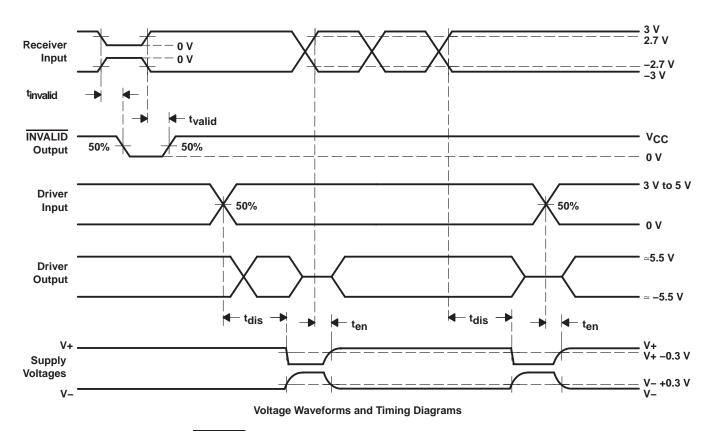
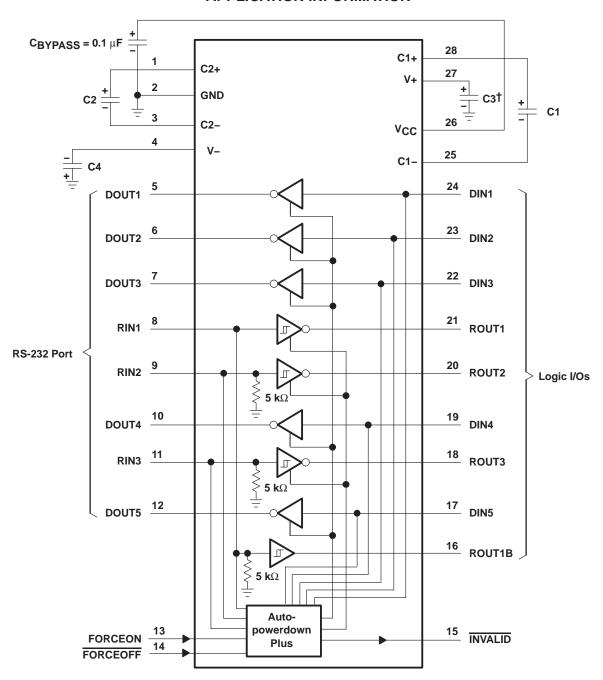


Figure 5. INVALID Propagation-Delay Times and Supply-Enabling Time



#### **APPLICATION INFORMATION**



**V<sub>CC</sub>** vs CAPACITOR VALUES

†C3 can be connected to V<sub>CC</sub> or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

VCC	C1	C2, C3, and C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.15 V} \\ \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.22 μF 0.047 μF 0.22 μF	0.1 μF 0.22 μF 0.33 μF 1 μF

Figure 6. Typical Operating Circuit and Capacitor Values



# DB (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

# PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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